



16MB Flash MCP Qualification W72M64V-XBX Quality and Reliability Report

2M x 64 FLASH PBGA MULTI-CHIP PACKAGE CONSTRUCTION

ORGANIZATIONS

- 2M x 64 Flash

ENCAPSULANT

- The encapsulant is not injection molded to control wire sweep effects
- $T_G = 150^\circ\text{C}$
- Moisture sensitivity is to JEDEC level 3

INTERPOSER MATERIAL

- CTE = 12-13 ppm / °C
- Water absorbtion = 0.13%

BALLS

- Eutectic solder Sn63/Pb37
- Diameter = 0.762mm (0.030) Typical

TEST

- Burn-In - 100%-48 hours at 125°C
- Final Electrical Test - 100% at maximum and minimum ambient temperatures

Temperature Ranges Available:

- 55°C to +125°C
- 40°C to +85°C
- 0°C to +70°C

SHIPPING

- Final bake out
- Shipped in JEDEC standard trays and anti-static shielded dry pack bags
- Humidity indicator cards are included
- Desiccant used in dry packs

Qualification Information

Qual for 219 PBGA Product

Qual Test	# of Pieces	Duration	Reference Standards	Temp. Range	Results
Preconditioning	All Test Sample		EIA/JESD22 Method A113 (level3)		Passed
Bias Life Test	15	1,000 hrs	EIA/JESD22 Method A108	125°C	15 Passed
Temperature Cycle	15	1,000 cycles	EIA/JESD22 Method A104 Condition B	-55°C to +125°C	15 Passed
85/85 Bias	15	1,000 hrs	EIA/JESD22 Method 101	85°C/85RH	15 Passed

(Per Reliability Report
200 A 0004-19)